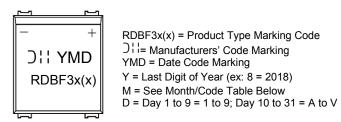


Marking Information



Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D

Maximum Ratings and Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic		Symbol	RDBF31	RDBF32	RDBF34	RDBF36	RDBF38	RDBF310	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} VR	100	200	400	600	800	1000	V
RMS Reverse Voltage		V _{R(RMS)}	70	140	280	420	560	700	V
Average Rectified Output Current (Note 5)	@T _C =+120°C	lo			3.	.0			А
Non-Repetitive Peak Forward Surge Current, Single Half Sine-Wave Superimposed on Rate	I _{FSM}	100						А	
I ² t Rating for Fusing (1ms < t < 8.3ms)	l ² t	41.5						A ² S	
Maximum Forward Voltage (Per Element)	@I _F =2.5A	V_{FM}			1.	.3			V
Maximum Reverse Recovery Time (Note 7)	t _{RR}		150		250	5	00	ns	
Peak Reverse Current At Rated DC Blocking Voltage	I _R	5.0 500						μA	
Typical Total Capacitance (Per Element) (Note	CT			4	5			pF	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 6) (Per Element)	R _{θJA}	15	°C/W
Typical Thermal Resistance, Junction to Case (Per Element)	R _{θJC}	5	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

Notes:

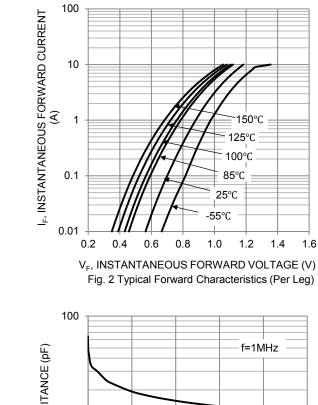
Device mounted on glass epoxy PC board with 1.3mm² solder pad.
Device mounted on 15mmx12mmx1.6mm Al pad attach 195mmx110mmx10mm steel plate.
Reverse recovery test conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A
Measured at 1.0MHz and applied reverse voltage of 4.0V D.C.

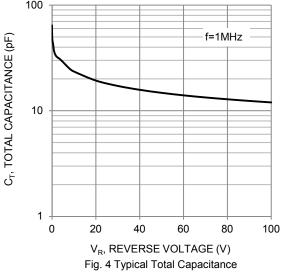


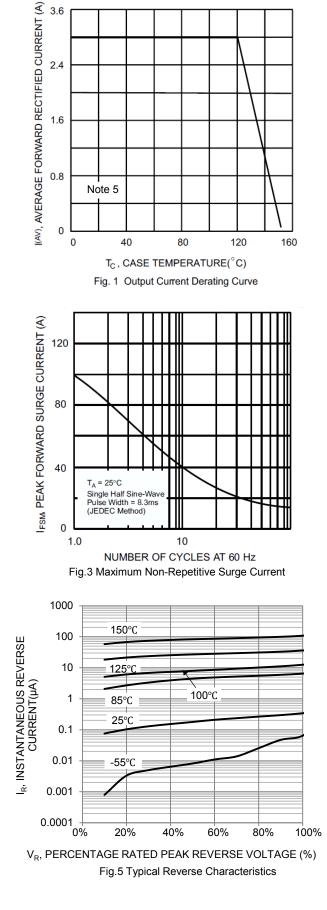
3.6

2.4





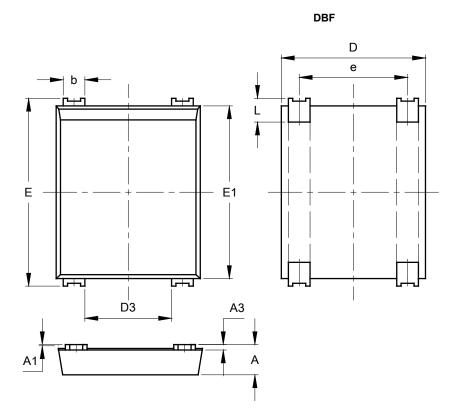






Package Outline Dimensions

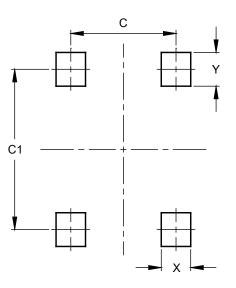
Please see http://www.diodes.com/package-outlines.html for the latest version.



Dim	Min	Max		
Α	1.30	1.50		
A1	0.04	0.12		
A3	0.15	0.35		
b	0.80	1.20		
D	6.45	6.85		
D3	3.80	4.20		
Е	8.50	8.90		
E1	7.50	8.20		
е	4.80	5.20		
L	0.50	1.50		
All dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version. DBF



Dimensions	Value (in mm)			
C	5.00			
C1	7.60			
Х	1.40			
Y	1.60			



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